

Abstract

The microcavity is delineated by a cover, comprising a first layer, in which at least one hole is formed. A second layer hermetically seals the microcavity. A third layer is arranged between the first and the second layer. An additional microcavity, communicating with the hole, is arranged between the first and the third layer. At least one additional hole, adjacent to the additional microcavity, formed in the third layer and offset with respect to the hole, is sealed by the second layer, after sacrificial layers have been removed through the additional hole. The microcomponent includes at least one mechanically stressed layer arranged above the first layer.